

The use of ACVIP Containment of the Accumulation of Program Technical Debt using AADL implemented on Dassault Systèmes' 3DEXPERIENCE Platform

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Agenda

Software Enabled Capabilities Growth...





DoD, OSD, & Branches Moving to Model-Based Acquisition

By Legislative Edict: Increase Modularity and Reuse

- **Strategy**:
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- ▷ Family of Systems,
- Integrated Modular Avionics
- ▷ Modular Open Systems Approach (MOSA)
- ▷ Re-competeable
- Process:
- ▷ Architecture Centric Virtual Integration Process (ACVIP)
- Technology:
 - ▷ Architecture Analysis Design Language (AADL)
- Methods:
 - ▷ Model Based Systems Engineering (MBSE)
 - ▷ Platform, Systems, Software Product Lines
 - ▷ System Theoretic Process Analysis (STPA)
 - ▷ Digital Thread to Virtual Twin

- Frameworks:
 - ▷ Open Systems Architecture (OSA)*
 - ► Joint Common Architecture (JCA)
 - ▷ Reference Architecture (RA)
 - Mission Level Capabilities
 - Mission Computer (MC) Conceptual Subsystem
 - ► Future Airborne Capability Environment (FACE)**
 - Military Community Application Software Product Lines
 - ► Hardware Open Systems Technology (HOST)

*, **, Two Great AHS Papers: Koontz, Johnson in Notes.



Concepts and Terms

- Goal: Creating a system that holds the potential to contain the accumulation of Technical Debt.
- Technical debt is accumulated when activities are done out of order. Sometimes this is deliberate sometimes not. When it is deliberate there is typically an activity in the plan to pay down the technical debt and the associated accumulation of the interest against that debt.
 - In the complex acquisition environment, we have also developed the concept of <u>Contextual Debt</u>. This results from the <u>program contextual complexity</u>, extending Technical Complexity to Program and Acquisition Context, Compounded by Reuse Across Systems, Platforms, Branches, and Lifecycle.
- There needs to be a strategy and plan, and enterprise architecture that is adopted to contain not just the technical debt but the contextual debt.



Extending the Concept of Technical Debt to Contextual Debt

🔰 #DevBootcamp / #TechnicalDebtTrap / @DocOnDev			
a the last standard the second		Reckless	Prudent
Shipping first-time code is like going into debt. A little debt speeds development so long as it is paid back promptly with a re-write.		"We don't have time for design"	"We must ship now and deal with consequences"
The danger occurs when the debt is not repaid. Every minute spent on not-quite-right code	- WARD CUNNINGHAM	Deliberate	
counts as interest on that debt.	OOPSLA '92	Inadvertent	
Sources of Technical Debt			"Now we know how we
Business Pressures	Parallel development	"What's Layering?" should	should have done it"
Lack of process or understanding	Delayed refactoring		
Lack of building loosely coupled	Lack of alignment to standards		1
components	Lack of knowledge		
Lack of a test suite	Lack of ownership		
Lack of documentation	Poor technological leadership		
► Lack of collaboration	Last minute specification changes		
Dearth of Knowledge-Sharing			
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Technical vs Contextual Complexity

Acquisition Innovation needs to consider the technical and contextual enablement.









A "Digital Enterprise" Infrastructure is NEEDED

MBSE, PLe/M, FoS, FoF: Value Creation, Delivery, and Capture

- Model-Based Systems Engineering (MBSE) enables maximal delivered value when it is tied in with the enterprise.
- Connecting MBSE into the enterprise is eased and more effective if there is already in place Digital Enterprise (DE) infrastructure. The DE connects the digital thread, and orchestration throughout the lifecycle.
- Systems and Software Product Line Engineering (PLe) integrated into the DE enables full captured value exploitation.
 - In addition, Ple-DE integration provides assurance of delivered value conforming to acquisition Product Line Management (PLMgt) best practices.
 - ▷ PLMgt facilities assurance of effective deliberate reuse which is the only *authorized means* to incremental Qualification/Certification.
 - ▷ Taken together PLe and PLMgt constitute Product Line Enterprise (PLE) with implications on management of the factory of the future (FoF).
- ► Family of Systems (FoS) management needs to be directly addressed by the DE in order to effectively execute acquisition best practices.
 - Management of the Contextual Complexity of FoS without a digital enterprise will spawn compensating behaviors built upon compensating behaviors over the program duration due to enterprise architecture obstruction (inadequacies).

Superposition of Value Initiatives





3DEXPERIENCE Digital Enterprise Platform for Multi-Scales Systems Engineering





ACVIP-AADL implementation on Dassault Systèmes' 3DEX Platform



ACVIP** Is Key To Earlier Error Detection & Elimination

- Model the complete system
 - ⊳ <u>One</u> comprehensive architecture
 - > Heterogeneous component models
- Execute the system virtually
 Models replaced by SIL* and HIL*
- ► Find, as early as possible, errors in:
 - Modularity, connectivity, signals, timing, physics
- ► Rinse and repeat until physical test
 - \triangleright Of which as little as possible
- *SIL Software in-the-loop; HIL – Hardware in-the-loop; **ACVIP – Architecture Centric Virtual Integration Process





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<u>3DEX Support: Authoritative Source of Truth For ACVIP</u>



<u>3DEX Support:</u> Single, Shareable Systems Model For ACVIP



<u>3DEX Support:</u> The Systems Model In Day-to-Day Context



3DEX Support: Systems Modeling On An Enterprise Foundation



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3DEX Support: System, Hardware, Software Architecture Modeling and Simulation supporting AADL (Specification + Annexes)







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Functional Architecture in 3DEXP – Electrical & Electronics App





Hardware Architecture in 3DEXP – EEA* App Context: Flight Data Management



*EEA – Electrical and Electronics Architecture



System mapping in 3DX – EEA App

Context: Flight Data Management



EEA App / AADL objects relationship





EEA / AADL objects relationship

Short description



EEA / AADL Translator





AADL Inspector: Execution









Future Work





Key Take-Aways

- Delivering on the Business Promise Depends on the Ability to Address Both <u>Technical</u> and <u>Contextual</u> Complexity.
- Approaches to address the ACVIP <u>Containment of the Accumulation</u> of Program Technical Debt are key; considerations include:
 - ▷ Modeling and Analysis with AADL in the same Digital Enterprise Platform
 - ▷ Early Schedulability budgeting and re-budgeting
 - ▷ Early Systems Safety Assessment based on Functions <u>AND</u> Design
- ▶ 3DEXPERIENCE, the Digital Enterprise platform, offers unique capabilities to address the ACVIP's goals:
 - ▷ Early identification of defects and integration issues
 - ▷ Authoritative Source of truth for ACVIP
 - Multiple Dimensions of Differentiation: Expressability, Precision, Constructability, Interoperability, Usability, Adaptability, Predictability, Simulateability, Decisionability
 - A platform that fully integrates the cross-discipline Requirements Validation, Modeling, Design, Simulation, Verification, and Certification
 - ▷ Adoption by government and industry



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- ► 3DEXPERIENCE: https://www.3ds.com/products-services/3dexperience/





